

FOR IMMEDIATE RELEASE

Remtec's Large Size Leadless SMT Ceramic Packages for Direct PCB Mount Provide Reliable, Low Cost Interconnects in a Broad Frequency Range.

Norwood, MA. May 12, 2006. Remtec's proprietary Plated Copper on Thick Film (PCTF®) technology permits the design and manufacture of leadless ceramic chip carriers and packages larger than .75 inch on a side. These packages, with unique wrap-around interconnections, plugged via holes, hermetic-filled vias and integrated passives, provide improved electrical and thermal performance at lower cost for high circuit/ power density applications.

PCTF technology with its ductile structure of plated copper over thick film on ceramic, results in minimizing solder joint stresses during assembly of ceramic packages to PC boards. Therefore, Remtec's leadless ceramic SMT packages with wraparounds for a direct PCB mount can be .75 X .75" in size or larger.

Wrap-around interconnections also eliminate use of leads and additional interface boards thus further reducing cost. In addition, they ensure low inductance package connections and can operate at frequency range above 32 GHz. These robust and reliable connections are ideal for SMT soldering and allow simple visual inspection and high assembly yields.

Plugged hermetic via holes with low resistance (less than 1 milliohm) provide for low RF losses below .1dB at 4 GHz and are excellent for ground and signal connections. Also, high thermal conductivity of vias (greater than 200 W/M x °C) results in low thermal resistance path providing excellent thermal management. Depending on a die size and ceramic package thickness, thermal resistance of 1-2 °C/W and lower can be achieved.

Plugged hermetic vias assure package integrity and reliability. They also allow the creation of fully hermetic Integral Substrate Packages (ISP) which is surface mountable.

Integrated resistors, capacitors and inductors can be often incorporated into SMT packages to reduce size and increase integration level.

In addition, Remtec packages are compatible with all standard interconnect assembly techniques including soldering, high temperature die attach, welding and wire bonding. Low tooling and fast turnaround time permit microcircuit designers to bring custom SMT packages into production quicker and with lower engineering costs.

Remtec, a RoHS compliant company, provides ceramic leadless SMT packages for LNA's, power amplifiers, switches, transceivers, mixers, tuners, splitters, filters, resistors, attenuators and terminations as well as for other components in a broad frequency range.

